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2826
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No.: Q64096

Yoshihiro NAKAJIMA, et al.

Allowed: February 27, 2004

Appln. No.: 09/941,744

Group Art Unit: 2826

Confirmation No.: 7388

Examiner: Pershelle L. GREENE

Filed: August 30, 2001

For: SEMICONDUCTOR DEVICE WITH UNEVEN
METAL PLATE TO IMPROVE ADHESION TO
MOLDING COMPOUND (as amended)

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §§ 1.97 and 1.98

MAIL STOP ISSUE FEE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant hereby notifies the U.S. Patent and Trademark Office of the documents which are listed on the attached PTO/SB/08 A & B (modified) form and/or listed herein and which the Examiner may deem material to patentability of the claims of the above-identified application.

One copy of each of the listed documents, with the exception of reference number 1 below (cited by the Examiner in Paper No. 6), is submitted herewith, along with a copy of the corresponding Communication from the European Patent Office dated January 21, 2004.

04/16/2004 JGALINAH 00000053 09941744

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INFORMATION DISCLOSURE STATEMENT

U.S. Appln. No.: 09/941,744

Atty. Docket No.: Q64096

1. U.S. Patent No. 6,040,626, dated March 21, 2000, to Chuan CHEA, et al. A copy of this reference is not being submitted herewith, as the Examiner cited this reference in the Office Action dated April 24, 2002 (paper no. 6).

2. U.S. Patent No. 4,862,246, dated August 29, 1989, to Masachika MASUDA, et al.

3. U.S. Patent No. 5,252,855, dated October 12, 1993, to Yoshiaki OGAWA, et al.

4. U.S. Patent No. 6,043,108, dated March 28, 2000, to Atsuhiko IZUMI, et al.

5. U.S. Patent No. 5,359,872, dated November 1, 1994, to Masayuki NASHIKI.

6. European Patent Publication No. 0 687 008 A2, dated December 13, 1995.

7. BINDRA, Ashok, "Innovative Packages Maximize MOSFETs' Thermal Performance," *Electronic Design*, Penton Publishing, Cleveland, OH, U.S, vol. 47, no. 10, May 17, 1999.

The present Information Disclosure Statement is being filed after either a Final Office Action, Notice of Allowance, or an action that otherwise closes prosecution in the application (whichever is earlier), but before payment of the Issue Fee, and therefore Applicant is submitting herewith a check for the fee of \$180.00 under 37 C.F.R. § 1.17(p), and a Statement Under 37 C.F.R. § 1.97(e).

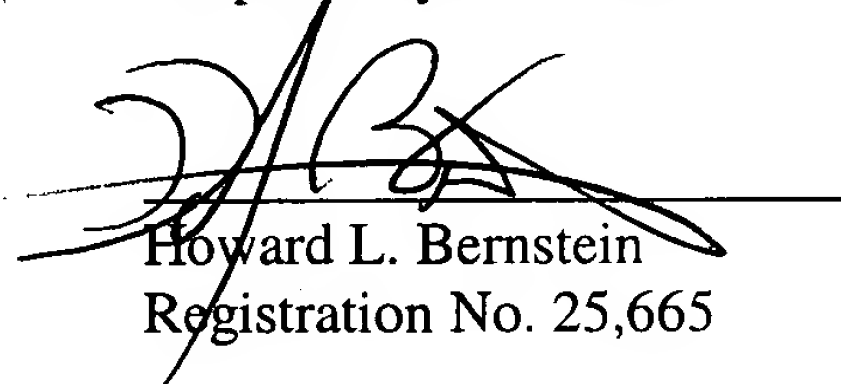
The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant does not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application.

INFORMATION DISCLOSURE STATEMENT
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The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account. A duplicate copy of this paper is attached.

Respectfully submitted,



Howard L. Bernstein
Registration No. 25,665

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: April 15, 2004

Substitute for Form 1449 A & B/PTO

Complete if Known

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet

1

of

1

Application Number	09/941,744
Confirmation Number	7388
Filing Date	August 30, 2001
First Named Inventor	Yoshihiro NAKAJIMA
Art Unit	2826
Examiner Name	Pershelle L. GREENE
Attorney Docket Number	Q64096

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code ² (if known)		
		US 4,862,246		08-29-1989	Masachika MASUDA, et al.
		US 5,252,855		10-12-1993	Yoshiaki OGAWA, et al.
		US 6,043,108		03-28-2000	Atsuhiko IZUMI, et al.
		US 5,359,872		11-01-1994	Masayuki NASHIKI
		US			
		US			
		US			
		US			
		US			

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation ⁶
		Country Code ³	Number ⁴	Kind Code ⁵ (if known)			
		EP	0 687 008 A2		12-13-1995	MOTOROLA, INC.	

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation ⁶
		BINDRA, Ashok, "Innovative Packages Maximize MOSFETs' Thermal Performance," <i>Electronic Design</i> , Penton Publishing, Cleveland, OH, U.S, vol. 47, no. 10, May 17, 1999.	

Examiner Signature

Date Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Applicant's unique citation designation number (optional). ²See Kind Codes of USPTO Patent Documents at www.uspto.gov, MPEP 901.04 or in the comment box of this document. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST. 3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶Applicant is to indicate here if English language Translation is attached.



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STATEMENT UNDER 37 C.F.R. § 1.97(e)

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P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The undersigned hereby states, upon information and belief:

That each item of information contained in the Information Disclosure Statement filed concurrently herewith was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of said Information Disclosure Statement.

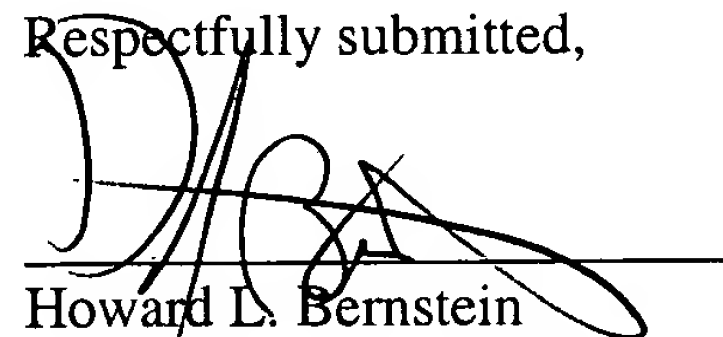
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Telephone: (202) 293-7060
Facsimile: (202) 293-7860

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